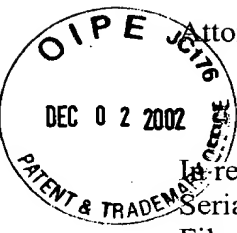


3728



Attorney Docket No. 5649-885

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Shim et al.
Serial No.: 09/903,070
Filed: July 11, 2001
For: METHODS OF PACKAGING SEMICONDUCTOR WAFERS BY MOLDING A
PACKING BAG ABOUT A CARRYING DEVICE THAT CONTAINS THE
SEMICONDUCTOR WAFERS

Confirmation No.: 9380
Group Art Unit: 3728
Examiner: Anthony D. Stashick

Handwritten: 4/11/02, See, 6/11/02, 12/9/02

Date: November 27, 2002

BOX NON-FEE AMENDMENT
Commissioner for Patents
Washington, DC 20231

RECEIVED
DEC - 5 2002
TECHNOLOGY CENTER R3700

FIRST RESPONSE BY APPLICANTS

Sir:

This is a full and timely response to the non-final Office Action mailed August 29, 2002 (Paper No. 3) that contains amendments and remarks as set forth hereafter. Attached hereto is a marked up version of the changes made to the claims by the current amendments. The marked up version of the changes is captioned "**VERSION WITH MARKINGS TO SHOW CHANGES MADE.**"

In the Claims:

Please enter amended Claims 1, 2, 5, 7, 8, 11, 15, 16, and 20 as follows:

Handwritten: a'

1. (Amended) A method for packing wafers comprising the steps of:
putting a cassette in which wafers are inserted, into a packing bag; and
sealing the packing bag by contacting an outer surface of the packing bag, opposite the cassette, so as to allow the packing bag to be tightly adhered along an external form of the cassette, molding a border of the packing bag and cutting an unnecessary border of the packing bag.
2. (Amended) The method for packing wafers according to Claim 1, wherein putting the cassette in which wafers are inserted, into the packing bag comprises:
putting the cassette in which 300 mm caliber wafers are inserted, into the packing bag.